WHAT IS CLAIMED IS:

1. A conveying apparatus comprising:

a holding plate having a holding surface destined to face a surface to be held of a wafer;

a restriction member provided on one end side of the holding surface, the restriction member adapted to contact a peripheral surface of the wafer so as to restrict movement of the wafer toward the one end side; and

means for moving the holding plate,

wherein a non-contact type suction holding part is formed at the holding surface, the suction holding part adapted to jet a fluid obliquely to the surface to be held of the wafer so as to move the wafer in a direction toward the restriction member and to generate a negative pressure between the holding surface and the surface to be held, thereby holding the wafer by suction, and

the fluid is jetted from the suction holding part so as to abut the wafer against the restriction member, thereby positioning the wafer at a predetermined position on the holding plate;

wherein a sensor for detecting a notch indicative of crystal orientation of the wafer is disposed at a position corresponding to the peripheral surface of the wafer,

the suction holding part includes:

a first suction holding part connected to a fluid supply source through a first suction path provided with a first opening control valve for controlling flow rate, the first suction holding part adapted to jet the fluid in a direction for rotating the wafer in a first rotating direction; and

a second suction holding part connected to the fluid supply source through a second suction path provided with a second opening control valve for

controlling flow rate, the second suction holding part adapted to jet the fluid in a direction for rotating the wafer in a second rotating direction opposite to the first rotating direction, and

an opening of one of the first opening control valve and the second opening control valve is set to be greater than an opening of another of the first opening control valve and the second opening control valve so as to rotate the wafer in the first rotating direction or the second rotating direction, and, after detection of the notch by the sensor, the opening of the first opening control valve or the second opening control valve is controlled so as to stop rotation of the wafer, thereby positioning the notch in a predetermined orientation relative to the holding plate.